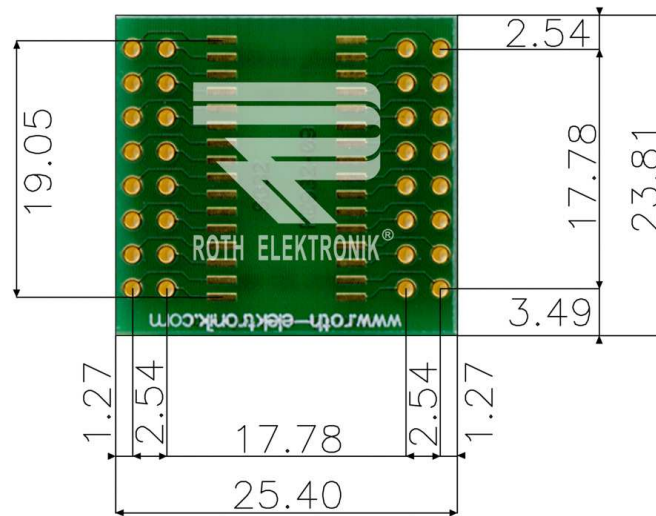


**RE932-09**

- Epoxy fibre-glass FR4 1.50 mm
  - Double-sided 35 µm Cu
  - Plated through holes (PTH)
  - Surface chem. Ni/Au with solder stop mask
  - Adaption circuit board for SO 32
  - Pitch: 1.27 mm (295 mil)
  - Hole diameter 1.00 mm
  - Size 23.81 x 25.40 mm
- Module-No. Pitch Pin Size (mm)

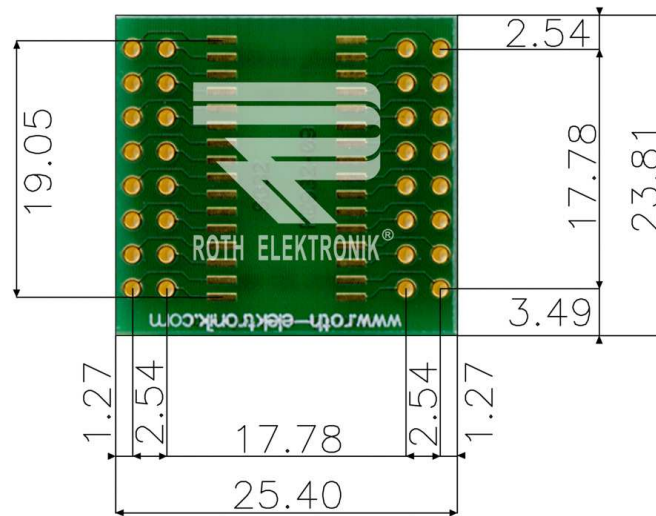
RE932-09 1.270 mm 0,50 32 7.50 (295 mil)



#### RE932-09

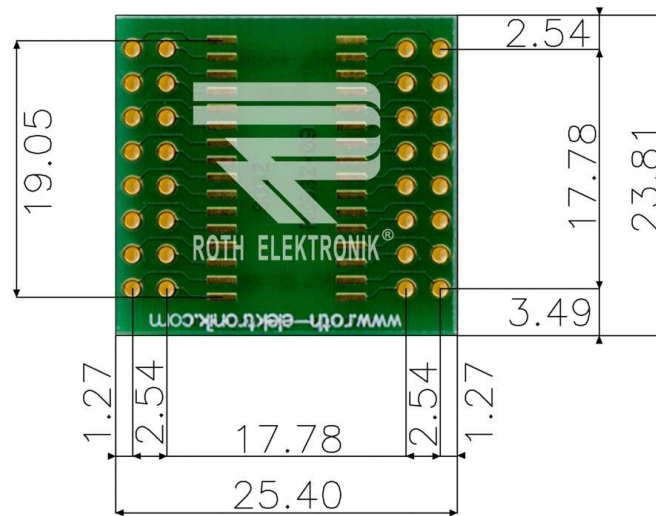
- Epoxydglashartgewebe FR4 1,50 mm
  - Zweiseitig 35 µm Cu
  - Durchkontaktiert (PTH)
  - Oberfläche chem. Ni/Au mit Lötstopplack beschichtet
  - Adaption Platine für SO 32
  - Pitch: 1,27 mm (295 mil)
  - Lochdurchmesser 1,00 mm
  - Größe 23,81 x 25,40 mm
- Modul-Nr. Pitch Pin Größe (mm)

RE932-09 1,270 mm 0,50 32 7,50 (295 mil)



#### RE932-09

- Fibre de verre époxyde FR4 1,50 mm
  - Double face 35 µm Cu
  - Métallisation des trous (PTH)
  - Surface avec Ni/Au chimique et un laque d'arrêt de soudure
  - Platine d'adaptation pour SO 32
  - Pitch: 1,27 mm (295 mil)
  - Perforation 1,00 mm Ø
  - Dimensions 23,81 x 25,40 mm
- Module-No. Pitch mil Pin Dimensions (mm)  
RE932-09 1,270 mm 0,50 32 7,50 (295 mil)



#### RE932-09

- Fibra de vidrio epoxídica FR4 1,50 mm
  - Por dos lados 35 µm de Cu
  - Agujeros con contactos metalizados (PTH)
  - Superficie terminal química de Ni/Au y una máscara de inhibidora de la soldadura
  - Adaptador para SO 32
  - Pitch: 1,27 mm (295 mil)
  - Diámetro de agujeros 1,00 mm
  - Tamaño 23,81 x 25,40 mm
- Módulo-No. Pitch mil Pin Tamaño (mm)  
RE932-09 1,270 mm 0,50 32 7,50 (295 mil)